

N-Channel JFET 40 V, 55 to 95 μA, 0.10 ms, CP **2SK545**

CASE 318BJ

Features

- Small IGSS
- Small C_{iss}
- Ultrasmall Package permitting 2SK545-applied Sets to be Compact
- This is a Pb–Free Device

Applications

- Impedance Converter Applications
- Infrared Sensor

ABSOLUTE MAXIMUM RATINGS (at $T_A = 25$ °C)

Parameter	Symbol	Ratings	Unit
Drain-to-Source Voltage	V _{DSS}	40	V
Gate-to-Drain Voltage	V_{GDS}	-40	V
Gate Current	I _G	10	mA
Drain Current	I _D	1	mA
Allowable Power Dissipation	P_{D}	100	mW
Junction Temperature	TJ	125	°C
Storage Temperature	T _{STG}	-55 to +125	°C

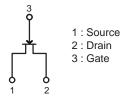
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

MARKING DIAGRAM



B11 = Specific Device Code

ELECTRICAL CONNECTION



ORDERING INFORMATION

Device	Package	Shipping [†]
2SK545-11D- TB-E	SC-59/CP3 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Table 1. ELECTRICAL CHARACTERISTICS (at T_A = 25°C)

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Gate-to-Drain Breakdown Voltage	V _{(BR)GDS}	$I_D = -10 \mu A, V_{DS} = 0 V$	-40			V
Gate Cutoff Current	I _{GSS}	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-500	pА
Drain Current	I _{DSS}	V _{DS} = 10 V, V _{GS} = 0 V	55		95	μΑ
Cutoff Voltage	V _{GS(off)}	$V_{DS} = 10 \text{ V}, I_D = 1 \mu A$		-1.2	-4.0	V
Forward Transfer Admittance	yfs	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ kHz}$	0.05	0.10		ms
Input Capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		1.7		pF
Reverse Transfer Capacitance	C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		0.7		pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

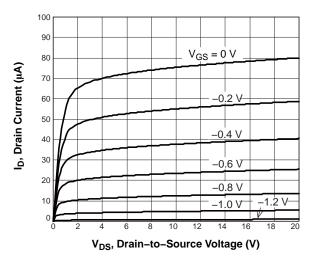


Figure 1. Drain Current vs. Drain-to-Source Voltage

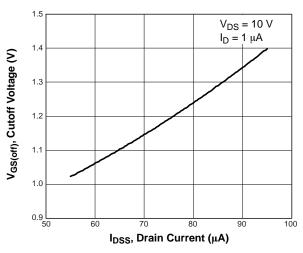


Figure 3. Cutoff Voltage vs. Drain Current

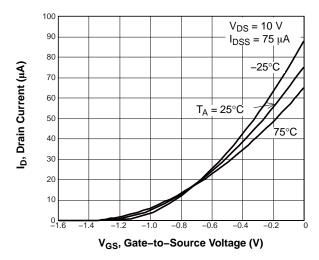


Figure 2. Drain Current vs. Gate-to-Source Voltage

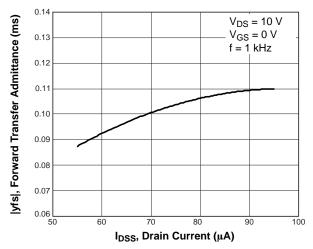


Figure 4. Forward Transfer Admittance vs. Drain Current

2SK545

TYPICAL CHARACTERISTICS

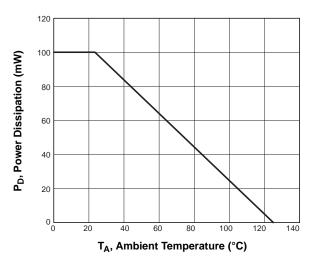


Figure 5. Power Dissipation vs. Ambient Temperature

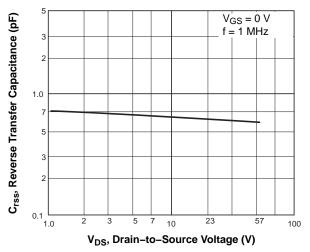


Figure 7. Reverse Transfer Capacitance vs. Drain-to-Source Voltage

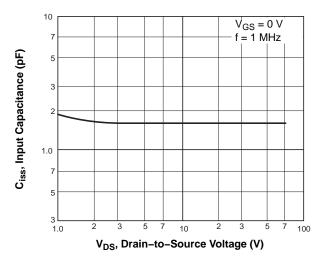


Figure 6. Input Capacitance vs. Drain-to-Source Voltage

MECHANICAL CASE OUTLINE

3X L

зх b

⊕ 0.10 M C A

C SEATING PLANE

Α

E1

е





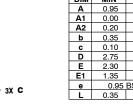
SC-59 / CP3 CASE 318BJ **ISSUE O**

DATE 09 JAN 2015

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER SIDE.
 4. DIMENSIONS D AND E1 ARE MEASURED AT THE OUTERMOST
- EXTREME OF THE PLASTIC BODY.
 DIMENSIONS 6 AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.20 FROM THE TIP.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.95	1.35	
A1	0.00	0.10	
A2	0.20	0.40	
b	0.35	0.50	
С	0.10	0.20	
D	2.75 3.05		
E	2.30 2.70		
E1	1.35 1.65		
е	0.95 BSC		
_	0.35	0.75	



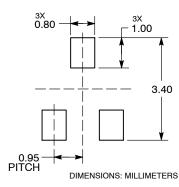
END VIEW

RECOMMENDED **SOLDERING FOOTPRINT***

SIDE VIEW

Δ1

TOP VIEW



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM



XXX = Specific Device Code

Μ = Date Code

= Pb-Free Package

(Note: Microdot may be in either location) *This information is generic. Please refer to

device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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DESCRIPTION:	SC-59 / CP3		PAGE 1 OF 1	

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